



Material Content Data Sheet



Sales Product Name	SPD07N60C3			Issued		23. January 2020		
MA#	MA000839164							
Package	PG-TO252-3-341			Weight*		383.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.883	1.27	1.27	12735	12735
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		179	
	non noble metal	iron	7439-89-6	0.229	0.06		598	
	non noble metal	copper	7440-50-8	228.946	59.71	59.79	597171	597948
wire	non noble metal	aluminium	7429-90-5	0.458	0.12	0.12	1194	1194
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.700	0.44		4434	
	plastics	brominated resin	-	1.821	0.48		4751	
	organic material	carbon black	1333-86-4	1.943	0.51		5068	
	plastics	epoxy resin	-	16.393	4.28		42759	
	inorganic material	silicondioxide	60676-86-0	99.574	25.97	31.68	259722	316734
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9755	9755
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1327	1327
solder	non noble metal	tin	7440-31-5	0.078	0.02		204	
	noble metal	silver	7440-22-4	0.098	0.03		256	
	non noble metal	lead	7439-92-1	3.742	0.98	1.03	9761	10221
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	5.00	5.00	50021	50086
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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